



# High Power Density Integrated Traction Machine Drive

## Fred Wang Oak Ridge National Laboratory May 11, 2011

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### Project ID: APE024

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# Overview

### Timeline

- Start Date: Jan. 2010
- End Date: Sept. 2013
- 30% Complete

## Budget

- Total project funding
  - DOE Share 100%
- Funding received in FY10
  - \$389K
- Funding for FY11
  - \$670K

### Barriers

- Barriers:
  - Simultaneously achieve high performance and fault tolerance while meeting high power density targets.
  - Ability to use low cost devices (Si) with acceptable high-temperature performance and reliability.
- Targets: DOE FreedomCAR 2020 power density (>4 kW/L) and efficiency (> 94%), 2015 cost (<\$12/kW)</li>

### Partners

- ORNL Team Members: Zhenxian Liang, Puqi Ning, and Laura Marlino
- University of Wisconsin motor & control
- University of Tennessee hightemperature packaging



# **Objectives**

 Develop a 55 kW high-density, fault-tolerant, integrated modular motor drive (IMMD) that is capable of operating at 200°C junction and 105°C coolant temperatures with improved packaging

### • FY11 Objectives

- Design and build a 10 kW demonstrator version IMMD with fault-tolerant controller to verify key performance characteristics
- Design and fabricate first version 200°C Si IGBT modules for IMMD implementation



# **Milestones**

Month/Year	Milestone or Go/No-Go Decision
June-2010	Milestone: Loss and thermal characterization of Si IGBT at 200°C
Sept-2010	Milestone: Candidate packaging technologies selection
Dec-2010	Milestone: Complete design of prototype 10 kW machine
Jan-2011	<i>Go/No Go Decision:</i> Design reviews to evaluate performance and fault tolerance capability, and to determine if prototype machine are ready for construction
April-2011	<i>Milestone</i> : Complete characterization of the Si IGBT operation at 200°C junction temperature
June-2011	Milestone: Fabricate a prototype 200°C Si IGBT phase-leg module
August-2011	<i>Milestone</i> : Complete construction and testing of low-power (10 kW) version demonstrator IMMD motor
Sept-2011	<i>Go/No-Go Decision</i> : Evaluate demonstrator IMMD test results to decide whether to proceed to full-scale 55 kW IMMD prototype in FY12; Determine whether the high-temperature phase-leg module can meet the full-power IMMD requirements



# **Approach/Strategy**

### Integrated Modular Motor Drive (IMMD) Concept



# Integration of modular machine-power electronics units in a combined single structure for density and cost gains

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#### Theoretical Limit for Si Devices (Ref. Buttay et al.)

**Device Packaging and Cooling** 

- Design device package to extend Si power modules to 200°C junction to meet temperature requirement for 105°C coolant in IMMD
- Eliminate baseplate and thermal interface material to reduce the thermal resistance, increase power density and save cost
- Integrate inverter and motor structure and cooling design
- Make use of the packaging research capability at ORNL and in collaboration with Power Device Packaging Project

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- Thorough comparative evaluation led to choice of 6-phase configuration with 12 stator slots and 10 poles, constructed with 6 stator phase modules. The choice considers the impact to the inverter.
- Selected machine exhibits attractive metrics in categories of power density, excitation frequency, module number, and rotor radial forces.
- A 10 kW demonstrator IMMD motor is under construction.

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### IMMD Fault-Tolerant Controller Architecture Development

### 5-Phase IMMD Demonstrator Unit Testbed



- Preferred fault-tolerant control architecture has independent controller for each phase
- All phase controllers share same sensor information and make decisions in parallel
- Algorithms being tested using available 5-phase IMMD testbed combined with TMS320F28035 32-bit microcontroller

Heterarchical Control Implementation of Field-Oriented Control for 6-Phase IMMD





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### Si IGBT Characterization and Evaluation at 200°C



## Nondestructive SOA verification board



Nondestructive latch-up current test board

Gate signal generation board



#### Latch-up current test at 250°C



- Selected 1200V/40A/175°C Si IGBT from Infineon for high temperature evaluation.
- Tested IGBT static and switching characteristics. Leakage current is high but losses are acceptable for operation at 200°C.
- Built the nondestructive SOA test board for latching and second breakdown evaluation.
- The IGBT can be successfully turned off without latching at 300A/250°C.



### High Temperature Device Packaging Development

- Designed a Si device based 10 kW phase-leg power module package including materials selection, layout design, parasitics extraction and thermal performance characterization.
- With a two-pass tube liquid cold plate, the analysis shows the package can meet the IMMD power and thermal performance requirement, considering different coolants and 150°C ambient.
- Designed a modular cooling structure for 6-phase inverter.



Layout design of 10 kW phase-leg module

Component	Dimension (mm)
IGC50T120T6RL	7.25×6.84×0.115
Emitter Pad	5.36×5.74×0.004
Gate Pad	1.31×0.81×0.004
SIDC42D120F6	6.5×6.5×0.12
Anode Pad	5.78×5.78×0.004
Substrate	30.6×30× (Cu: 0.3, Al <sub>2</sub> O <sub>3</sub> : 0.635)
Die Attachment	Solder Au80Sn20, thickness: 0.2
Aluminum Wires	Gate pad 5 mils, others 10mils×6

Materials Selection



Simulated cooling performance of the packaging design





### Fabricated First Version Custom Module



- ABB dies (1200V/75A/150°C)
- DBC: alumina
- Die attachment: Sn63Pb37, thickness 100 μm
- Copper bus and lead frame: thickness 10 mils
- Encapsulant: Nu-2188
- Module fabricated with support from Power Device Packaging Project

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#### IGBT Output Characteristics

#### DC Blocking Characteristics



### System-level Electrical Design

### Modular multiphase motor drive architecture



Version 1 phase-leg modules (with driver boards)



### Controller with carrier board

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- Controller board and carrier board hardware designed and built
- Version 1 converter using phase-leg modules based on commercial IGBT modules built and tested
- Power board designed and built

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# Collaboration

### • Partners

- University of Wisconsin: Subcontractor, design and develop integrated modular motor drive system
- University of Tennessee : Subcontractor, assist in design and testing power modules based on Si devices operating with 105°C coolant and 200°C junction temperatures



# **Future Work – FY11**

- Complete fabrication and test the 10 kW 6-phase demonstrator IMMD motor to verify the machine design
- Implement and test fault-tolerant controller in the demonstrator IMMD
- Complete experimental evaluation of Si IGBT shortcircuit and second breakdown characteristics at high temperatures
- Fabricate and test 10 kW high-temperature phase-leg power modules using Si devices appropriate for full power 55 kW IMMD
- Conduct system-level electrical and thermal design considering machine, device modules as well as passives and controllers under 105°C cooling conditions



# Future Work - FY12 and beyond

- Scale up the power level of the IMMD technology to design, build, and demonstrate a prototype 55 kW IMMD system meeting the performance targets
- Develop the power electronics needed for implementing the full power IMMD with 105°C coolant and junction temperatures up to 200°C
- Combine the machine with high-temperature power converter and test the complete drive
- Evaluate prototype drive test results against performance predictions to determine success of project





- The project is developing a high-density integrated modular motor drive that will meet DOE 2020 power density and efficiency targets and the 2015 cost target
- The design will utilize low cost Si devices and hightemperature packaging and will be capable of operating at 200°C junction temperature with 105°C coolant
- The key FY10-FY11 accomplishments include:
  - A 6-phase 10-pole machine configuration has been selected and a 10 kW prototype is under construction
  - A fault-tolerant controller is being implemented and tested
  - Selected commercial Si IGBTs have been characterized at 200°C with acceptable loss characteristics and safe-operating-area
  - A prototype high-temperature custom Si IGBT phase-leg module has been designed and fabricated

